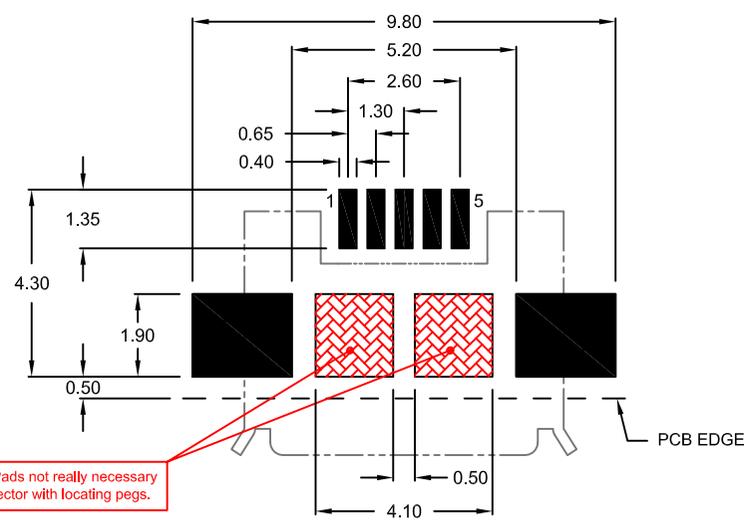
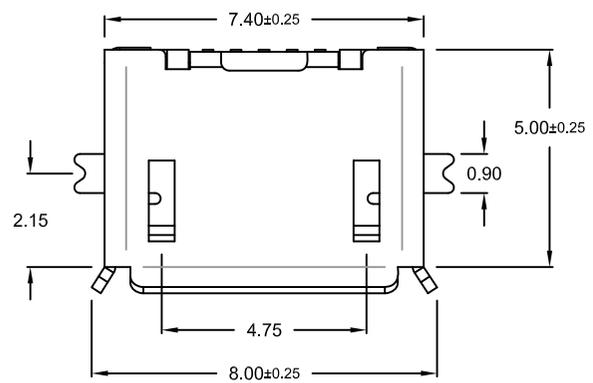


REV.	DESCRIPTION	DATE	DRAWN
A	New	30.03.2009	Ryan
B	Plating Code -98 --> -58	18.04.2013	Ryan
C	PN Code -SAB01- --> -SK0AB21-	06.02.2017	Ronny
D	general update	08.01.2019	Ronny

Recommended PCB Layout
(Tolerance: ±0.05)



Solder Pads not really necessary if connector with locating pegs.

Order Code
UNS-B05-SK0AB21-58/R

Specifications

Electrical
 Current rating: 1) Signal Line: 1.0A/contact (No. 2, 3, 4)
 2) Power Line: 1.8A/contact (No. 1 & 5)
 Insulation resistance: 100MΩ min. @ 500V DC
 Contact resistance: 30mΩ max. @ 100mA
 Voltage rating: 30V AC max.
 Withstanding voltage: 100V AC for 1 Minute

Material

Contact: PhBz t=0.20
 Plating: solder area Au flash, contact area Au 30μ"
 Shell: Stainless Steel t=0.25; Sn plated
 Insulator: LCP (GF 30%) UL 94V-0 (Black)

Operating temperature: -30°C to +80°C
 Processing temperature: +260°C +0/-5°C for 5 sec.

Mechanical

Durability (Life Time): 10.000 Cycles min.
 Insertion force: 35N max.
 Extraction force: 8N min.

Packing
Reel



Micro USB 2.0 Type "A & B"
 5-Contact Female - SMT horizontal Type
 with Wing Ground tabs
without locating pegs

A
B
C
D
E
F
G

A
B
C
D
E
F
G

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UNIT mm	GENERAL TOLERANCE		DRAWN Ryan	DATE 30.03.2009	DWG. NO. UNS-SK0AB21	SHEET 1/1
	X° ±	X. ±				
	.X° ±	.X ±				
	.XX° ±	.XX ± 0.13				
SCALE Free	.XXX° ±	.XXX ±	CHECK Hogi	DATE 21.01.2019	SERIES NO. UNS-B05-SK0AB21-xx/R	REV. D
APPROVE Hogi		DATE 21.01.2019				

1 2 3 4 5 6 7 8